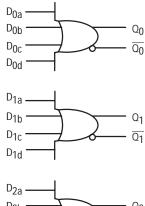
# Product Preview

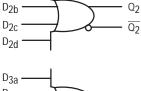
# **Quad 4-Input OR/NOR**

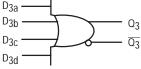
The MC10EP101 is a Quad 4–input OR/NOR gate. The device is functionally equivalent to the E101. With AC performance much faster than the E101 device, the EP101 is ideal for applications requiring the fastest AC performance available. All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to power supply to guarantee proper operation.

- 240ps Typical Propagation Delay
- High Bandwidth to 3 Ghz Typical
- PECL mode: 3.0V to 5.5V  $V_{CC}$  with  $V_{EE} = 0V$
- ECL mode:  $0V V_{CC}$  with  $V_{EE} = -3.0V$  to -5.5V
- 75kΩ Internal Input Pulldown Resistors
- ESD Protection: >2KV HBM, >100V MM
- Moisture Sensitivity Level 2
   For Additional Information, See Application Note AND8003/D
- Flammability Rating: UL-94 code V-0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 173 devices

#### LOGIC DIAGRAM







This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.



### ON Semiconductor

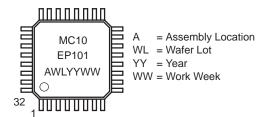
Formerly a Division of Motorola

http://onsemi.com



32-LEAD TQFP FA SUFFIX CASE 873A

#### **MARKING DIAGRAM\***



\*For additional information, see Application Note AND8002/D

PIN DESCRIPTION							
PIN	FUNCTION						
D0a-D3d	ECL Data Inputs						
Q0-Q3, Q0-Q3	ECL Data Outputs						
VCC	Positive Supply						
VBB	Reference Voltage Output						
VEE	Negative, 0 Supply						

## TRUTH TABLE

Dna	Dnb	Dnc	Dnd	Qn	Qn
L H X X X H	L Х Н Х	L X X Н	L X X H H		H

#### **ORDERING INFORMATION**

Device	Package	Shipping			
MC10EP101FA	TQFP	250 Units/Tray			
MC10EP101FAR2	TQFP	2000 Tape & Reel			

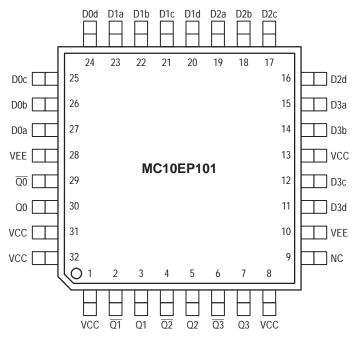


Figure 1. 32–Lead TQFP Pinout (Top View)

Warning: All  $V_{CC}$  and  $V_{EE}$  pins must be externally connected to Power Supply to guarantee proper operation.

### **MAXIMUM RATINGS\***

Symbol	Parameter		Value	Unit
VEE	Power Supply (V <sub>CC</sub> = 0V)		-6.0 to 0	VDC
V <sub>CC</sub>	Power Supply (V <sub>EE</sub> = 0V)		6.0 to 0	VDC
VI	Input Voltage (V <sub>CC</sub> = 0V, V <sub>I</sub> not more negative that	an V <sub>EE</sub> )	-6.0 to 0	VDC
VI	Input Voltage (VEE = 0V, VI not more positive than	n V <sub>CC</sub> )	6.0 to 0	VDC
l <sub>out</sub>	Output Current	Continuous Surge	50 100	mA
TA	Operating Temperature Range		-40 to +85	°C
T <sub>stg</sub>	Storage Temperature		-65 to +150	°C
θЈА	Thermal Resistance (Junction–to–Ambient)	Still Air 500lfpm	80 55	°C/W
θJC	Thermal Resistance (Junction-to-Case)		12 to 17	°C/W
T <sub>sol</sub>	Solder Temperature (<2 to 3 Seconds: 245°C desi	ired)	265	°C

 $<sup>^{\</sup>star}$  Maximum Ratings are those values beyond which damage to the device may occur.

### DC CHARACTERISTICS, ECL/LVECL ( $V_{CC} = 0V$ , $V_{EE} = -5.5V$ to -3.0V) (Note 3.)

			-40°C 25°C		85°C						
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current (Note 1.)					60					mA
Vон	Output HIGH Voltage (Note 2.)	-1135	-1060	-885	-1070	-945	-820	-1010	-885	-760	mV
VOL	Output LOW Voltage (Note 2.)	-1935	-1810	-1685	-1870	-1745	-1620	-1810	-1685	-1560	mV
VIH	Input HIGH Voltage Single Ended	-1210		-885	-1145		-820	-1085		-760	mV
V <sub>IL</sub>	Input LOW Voltage Single Ended	-1935		-1610	-1870		-1545	-1810		-1485	mV
lН	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current	-150			-150			-150			μΑ

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

- 1.  $V_{CC}$  = 0V,  $V_{EE}$  =  $V_{EEmin}$  to  $V_{EEmax}$ , all other pins floating. 2. All loading with 50 ohms to  $V_{CC}$  -2.0 volts.
- 3. Input and output parameters vary 1:1 with VCC.

## DC CHARACTERISTICS, LVPECL ( $V_{CC} = 3.3V \pm 0.3V$ , $V_{EE} = 0V$ ) (Note 6.)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current (Note 4.)					60					mA
VOH	Output HIGH Voltage (Note 5.)	2165	2240	2415	2230	2355	2480	2290	2415	2540	mV
VOL	Output LOW Voltage (Note 5.)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
VIH	Input HIGH Voltage Single Ended	2090		2415	2155		2480	2215		2540	mV
V <sub>IL</sub>	Input LOW Voltage Single Ended	1365		1690	1430		1755	1490		1815	mV
lН	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current	-150			-150			-150			μА

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

- 4.  $V_{CC} = 3.0V$ ,  $V_{EE} = 0V$ , all other pins floating.
- 5. All loading with 50 ohms to  $V_{CC}$  –2.0 volts.
- 6. Input and output parameters vary 1:1 with V<sub>CC</sub>.

## DC CHARACTERISTICS, PECL ( $V_{CC} = 5.0V \pm 0.5V$ , $V_{EE} = 0V$ ) (Note 9.)

			-40°C 25°C								
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current (Note 7.)					60					mA
VOH	Output HIGH Voltage (Note 8.)	3865	3940	4115	3930	4055	4180	3990	4115	4240	mV
VOL	Output LOW Voltage (Note 8.)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
VIH	Input HIGH Voltage Single Ended	3790		4115	3855		4180	3915		4240	mV
V <sub>IL</sub>	Input LOW Voltage Single Ended	3065		3390	3130		3455	3190		3515	mV
ΊΗ	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current	-150			-150			-150			μΑ

NOTE: 10EP circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse airflow greater than 500lfpm is maintained.

- 7.  $V_{CC}$  = 5.0V,  $V_{EE}$  = 0V, all other pins floating. 8. All loading with 50 ohms to  $V_{CC}$  -2.0 volts.
- 9. Input and output parameters vary 1:1 with V<sub>CC</sub>.

# AC CHARACTERISTICS (V<sub>CC</sub> = 3.0V to 5.5V; V<sub>EE</sub> = 0V) or (V<sub>CC</sub> = 0V; V<sub>EE</sub> = -3.0V to -5.5V)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency (Note 10.)		3.0			3.0			3.0		GHz
tPLH, tPHL	Propagation $D \rightarrow Q, \overline{Q}$ Delay		225			240			250		ps
tSKEW	Device Skew Q, Q Part-to-Part (Note 11.)		TBD TBD			TBD TBD			TBD TBD		ps
<sup>t</sup> JITTER	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
t <sub>r</sub> t <sub>f</sub>	Output Rise and Fall Times (20% – 80%) Q, Q					200 135			150		ps

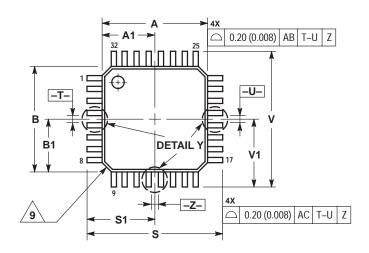
<sup>10.</sup> F<sub>max</sub> guaranteed for functionality only.

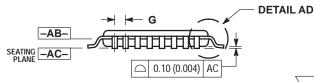
<sup>11.</sup> Skew is measured between outputs under identical transitions.

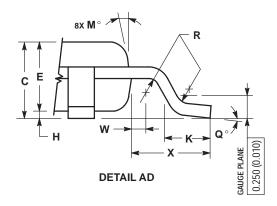
#### **PACKAGE DIMENSIONS**

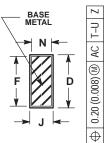
#### **TQFP FA SUFFIX**

32-LEAD PLASTIC PACKAGE CASE 873A-02 ISSUE A

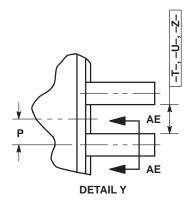








SECTION AE-AE



NOTES:

- 11. DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DATUM PLANE -AB- IS LOCATED AT BOTTOM
  OF LEAD AND IS COINCIDENT WITH THE LEAD
  WHERE THE LEAD EXITS THE PLASTIC BODY AT
  THE BOTTOM OF THE PARTING LINE.
  4. DATUMS -T., -U., AND -Z. TO BE
  DETERMINED AT DATUM PLANE -AB-.
  5. DIMENSIONS S AND Y TO RE DETERMINED AT
  5. DIMENSIONS S AND Y TO RE DETERMINED AT

- DE TERMINED AT DATUM PLANE -AB-.
  5. DIMENSIONS S AND V TO BE DETERMINED AT
  SEATING PLANE -AC-.
  6. DIMENSIONS A AND B DO NOT INCLUDE
  MOLD PROTRUSION. ALLOWABLE PROTRUSION
  IS 0.250 (0.010) PER SIDE. DIMENSIONS A AND B
- DO INCLUDE MOLD MISMATCH AND ARE
  DETERMINED AT DATUM PLANE -AB-.
  TO DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE D DIMENSION TO EXCEED 0.520 (0.020).
- u.520 (J.020).

  8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076 (0.0003).

  9. EXACT SHAPE OF EACH CORNER MAY VARY FROM DEPICTION.

	MILLIN	METERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
Α	7.000	BSC	0.276	BSC			
A1	3.500	BSC	0.138	BSC			
В	7.000	BSC	0.276	BSC			
B1	3.500	BSC	0.138	BSC			
С	1.400	1.600	0.055	0.063			
D	0.300	0.450	0.012	0.018			
E	1.350	1.450	0.053	0.057			
F	0.300	0.400	0.012	0.016			
G	0.800	BSC	0.031 BSC				
Н	0.050	0.150	0.002	0.006			
J	0.090	0.200	0.004	0.008			
K	0.500	0.700	0.020	0.028			
M	12°	REF	12° REF				
N	0.090	0.160	0.004	0.006			
Р	0.400	BSC	0.016	BSC			
Q	1°	5°	1°	5°			
R	0.150	0.250	0.006	0.010			
S	9.000	BSC	0.354	BSC			
S1	4.500	BSC	0.177 BSC				
V	9.000	BSC	0.354 BSC				
V1	4.500	BSC	0.177 BSC				
W	0.200	REF	0.008	REF			
Х	1.000	REF	0.039	REF			

# **Notes**

# **Notes**

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

#### PUBLICATION ORDERING INFORMATION

North America Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

EUROPE: LDC for ON Semiconductor - European Support

**German Phone:** (+1) 303–308–7140 (M–F 2:30pm to 5:00pm Munich Time)

Email: ONlit-german@hibbertco.com

French Phone: (+1) 303–308–7141 (M–F 2:30pm to 5:00pm Toulouse Time)

Email: ONlit-french@hibbertco.com

English Phone: (+1) 303–308–7142 (M–F 1:30pm to 5:00pm UK Time)

Email: ONlit@hibbertco.com

ASIA/PACIFIC: LDC for ON Semiconductor – Asia Support

Phone: 303–675–2121 (Tue–Fri 9:00am to 1:00pm, Hong Kong Time) Toll Free from Hong Kong 800–4422–3781

Email: ONlit-asia@hibbertco.com

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–8549

**Phone**: 81–3–5740–2745 **Email**: r14525@onsemi.com

**Fax Response Line**: 303–675–2167

800-344-3810 Toll Free USA/Canada

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.